



High power cycling capability
Low on-state and switching losses
Designed for traction and industrial applications

Phase Control Thyristor Type T263-1000-52

Maximum allowable mean on-state current		I _{TAV}		1000 A	
Repetitive peak off-state voltage		V _{DRM}		4600...5200 V	
Repetitive peak reverse voltage		V _{RRM}			
Turn-off time		t _q		800 μs	
V _{DRM} , V _{RRM} , V	4600	4800	5000	5200	
Voltage code	46	48	50	52	
T _j , °C	-60...+125				

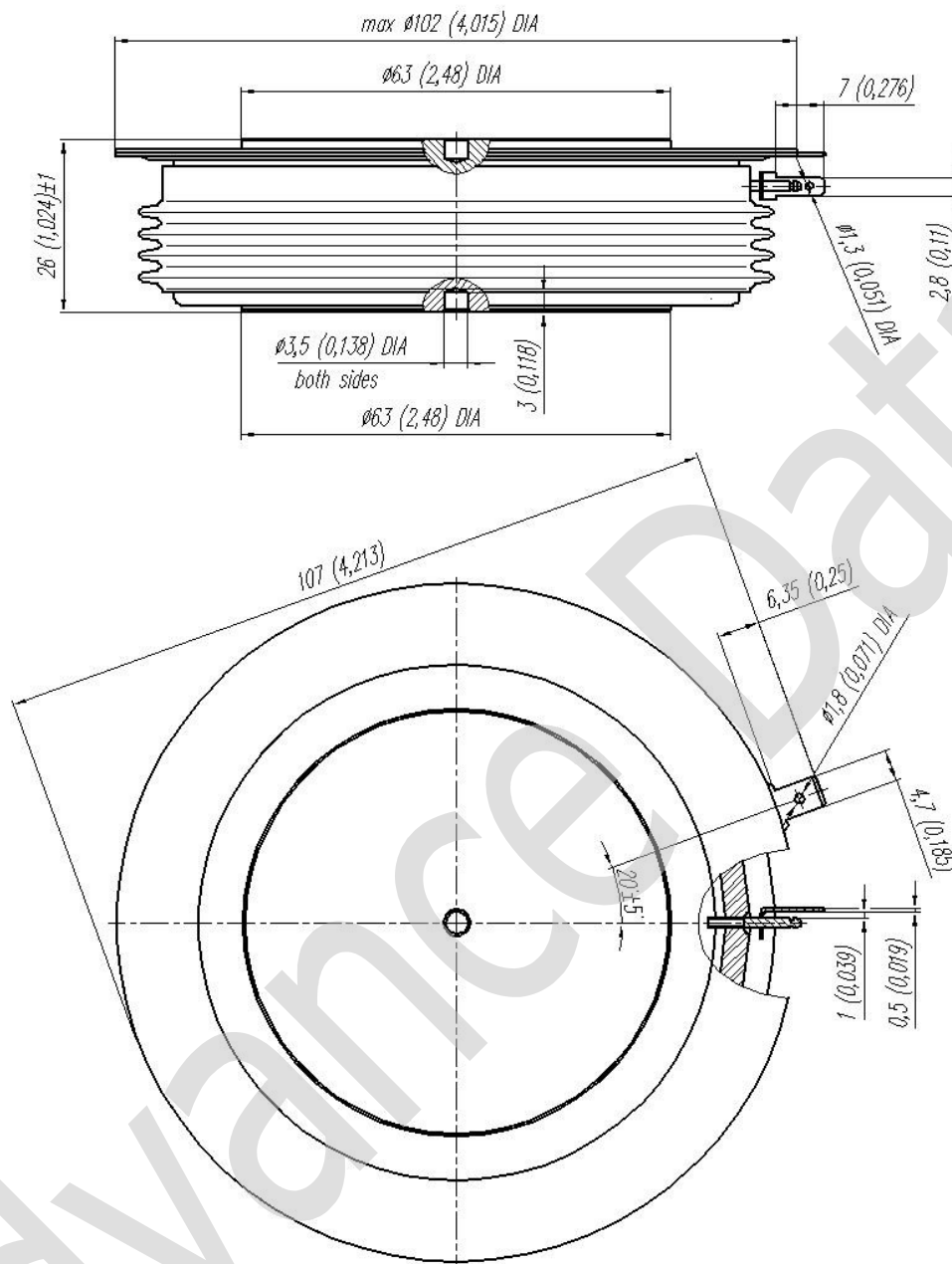
MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Maximum allowable mean on-state current	A	1000 1476	$T_c=104\text{ }^{\circ}\text{C}$, Double side cooled $T_c=85\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	1570	$T_c=104\text{ }^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	21.0 24.0	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{S}$; $di_G/dt\geq 1\text{ A}/\mu\text{S}$
			22.0 25.0	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{S}$; $di_G/dt\geq 1\text{ A}/\mu\text{S}$
I^2t	Safety factor	$\text{A}^2\text{s}\cdot 10^3$	2200 2800	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{S}$; $di_G/dt\geq 1\text{ A}/\mu\text{S}$
			2000 2500	$T_j=T_{j\text{ max}}$ $T_j=25\text{ }^{\circ}\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{S}$; $di_G/dt\geq 1\text{ A}/\mu\text{S}$
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	4600...5200	$T_{j\text{ min}}<T_j<T_{j\text{ max}}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	4700...5300	$T_{j\text{ min}}<T_j<T_{j\text{ max}}$; 180° half-sine wave; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.6\cdot V_{DRM}$ $0.6\cdot V_{RRM}$	$T_j=T_{j\text{ max}}$; Gate open	

TRIGGERING					
I_{FGM}	Peak forward gate current	A	8	$T_j=T_{j\ max}$	
V_{RGM}	Peak reverse gate voltage	V	5		
P_G	Gate power dissipation	W	5	$T_j=T_{j\ max}$ for DC gate current	
SWITCHING					
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive	$A/\mu s$	630	$f=1\ Hz$	$T_j=T_{j\ max};\ V_D=0.67\cdot V_{DRM};$ $I_{TM}=2\ I_{TAV};$ Gate pulse: $I_G=2\ A;$ $t_{GP}=50\ \mu s;$ $di_G/dt\geq 2\ A/\mu s$
			160	$f=50\ Hz$	
THERMAL					
T_{stg}	Storage temperature	$^{\circ}C$	$-60...+50$		
T_j	Operating junction temperature	$^{\circ}C$	$-60...+125$		
MECHANICAL					
F	Mounting force	kN	$33.0...40.0$		
a	Acceleration	m/s^2	50	Device clamped	

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V _{TM}	Peak on-state voltage, max	V	2.80	T _j =25 °C; I _{TM} =5000 A	
V _{T(TO)}	On-state threshold voltage, max	V	0.900	T _j =T _{j max} ;	
r _T	On-state slope resistance, max	mΩ	0.500	0.5 π I _{TAV} < I _T < 1.5 π I _{TAV}	
I _L	Latching current, max	mA	1500	T _j =25 °C; V _D =12 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs	
I _H	Holding current, max	mA	300	T _j =25 °C; V _D =12 V; Gate open	
BLOCKING					
I _{DRM} , I _{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	200	T _j =T _{j max} ; V _D =V _{DRM} ; V _R =V _{RRM}	
(dv _D /dt) _{crit}	Critical rate of rise of off-state voltage ¹⁾ , min	V/μs	1000	T _j =T _{j max} ; V _D =0.67·V _{DRM} ; Gate open	
TRIGGERING					
V _{GT}	Gate trigger direct voltage, max	V	5.00 3.00 2.00	T _j = T _{j min} T _j =25 °C T _j = T _{j max}	V _D =12 V; I _D =3 A; Direct gate current
I _{GT}	Gate trigger direct current, max	mA	500 300 200	T _j = T _{j min} T _j = 25 °C T _j = T _{j max}	
V _{GD}	Gate non-trigger direct voltage, min	V	0.35	T _j =T _{j max} ; V _D =0.67·V _{DRM} ;	
I _{GD}	Gate non-trigger direct current, min	mA	15.00	Direct gate current	
SWITCHING					
t _{gd}	Delay time	μs	4.00	T _j =25 °C; V _D =1500 V; I _{TM} =I _{TAV} ; di/dt=200 A/μs; Gate pulse: I _G =2 A; V _G =20 V; t _{GP} =50 μs; di _G /dt=2 A/μs	
t _q	Turn-off time ²⁾ , max	μs	800	dv _D /dt=50 V/μs; T _j =T _{j max} ; I _{TM} =I _{TAV} ; di _R /dt=-10 A/μs; V _R =100 V; V _D =0.67 V _{DRM} ;	
Q _{rr}	Recovered charge, max	μC	6680	T _j =T _{j max} ; I _{TM} =1000 A;	
t _{rr}	Reverse recovery time, max	μs	85	di _R /dt=-5 A/μs;	
I _{rr}	Reverse recovery current, max	A	157	V _R =100 V	



All dimensions in millimeters (inches)

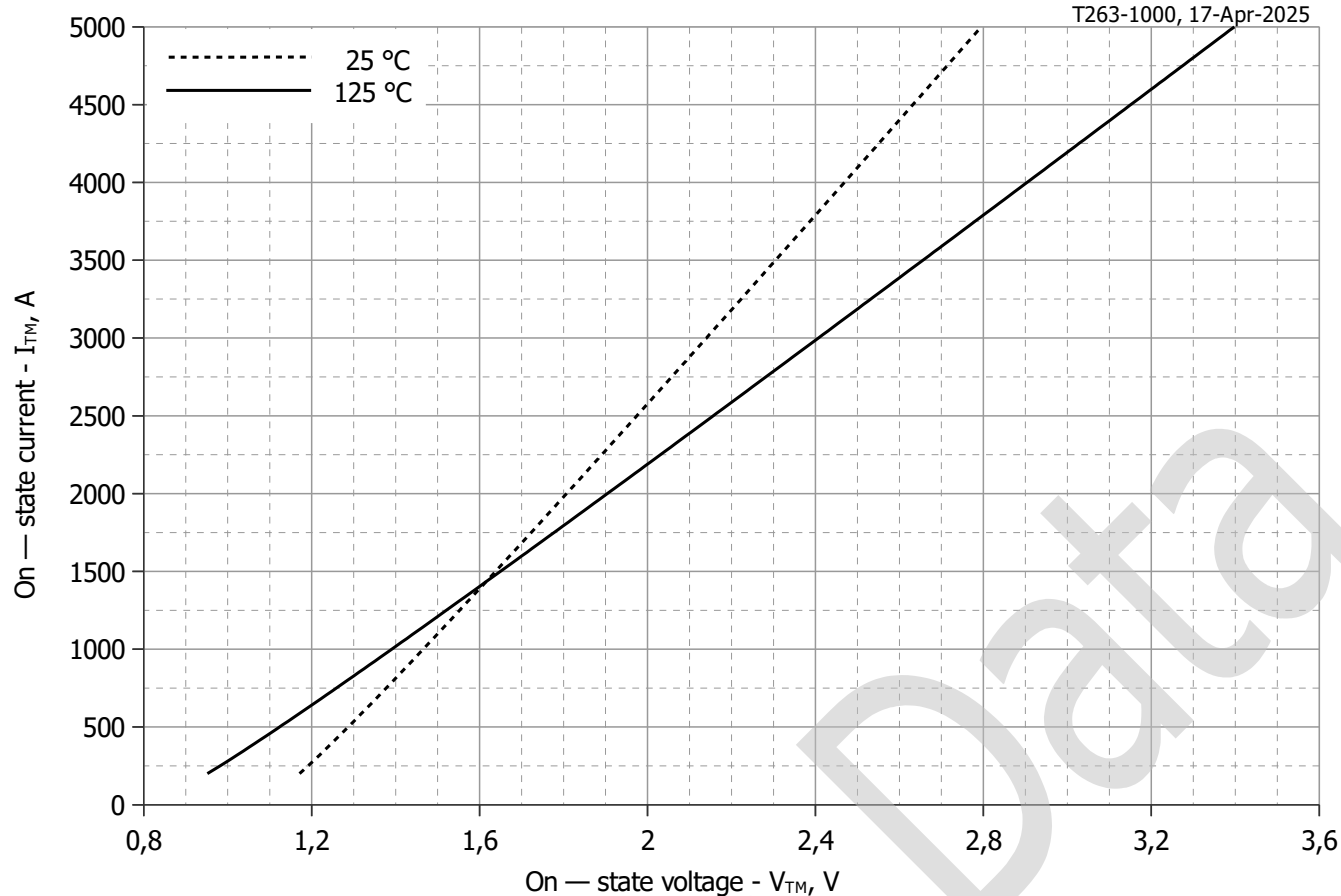


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	$T_j = 25^\circ\text{C}$	$T_j = T_{j\max}$
A	1.05299794	0.77805237
B	0.00030712	0.00047019
C	0.00428732	0.00718285
D	0.00240045	0.00293493

On-state characteristic model (see Fig. 1)

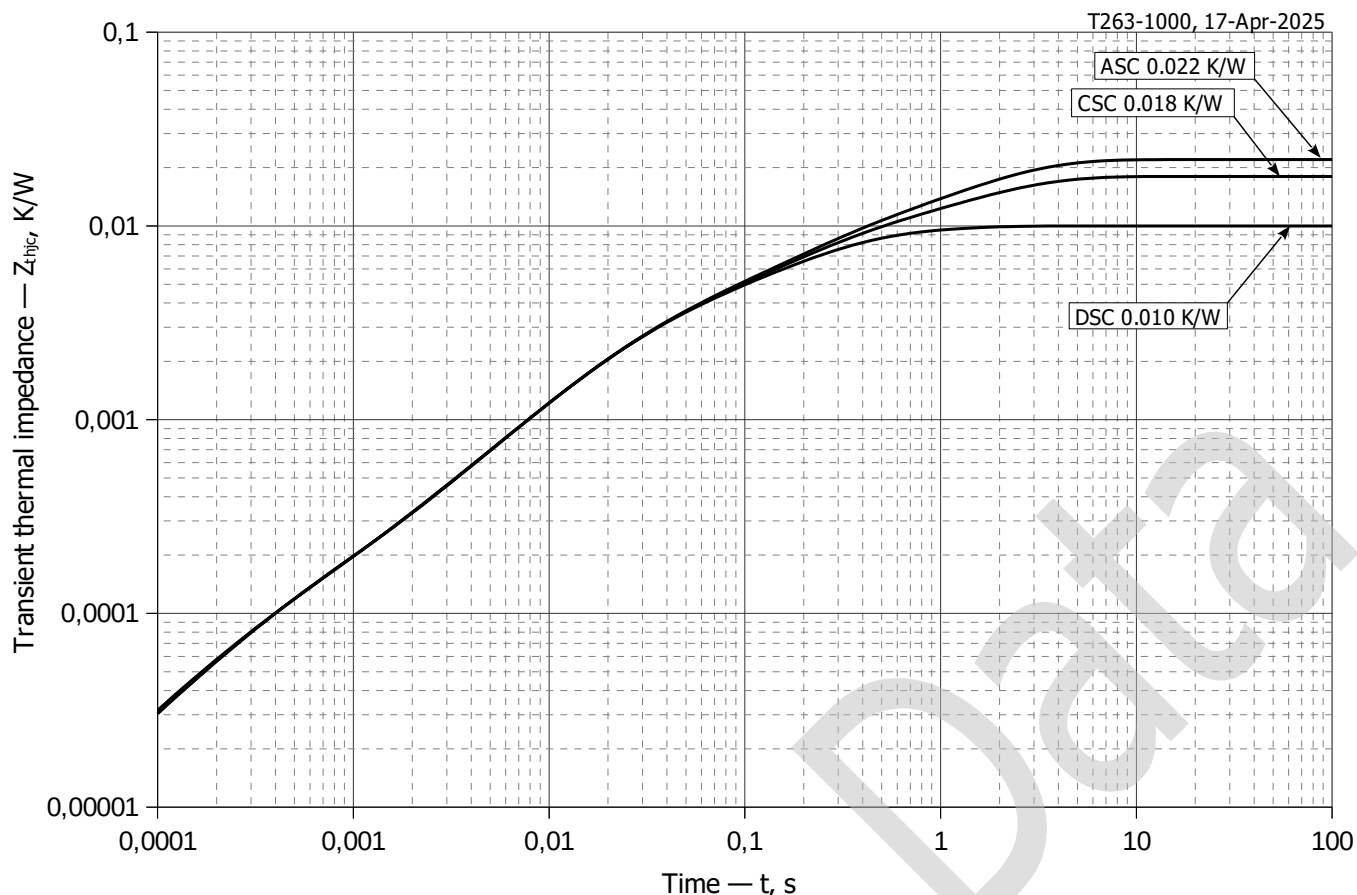


Fig 2 – Transient thermal impedance Z_{thjc} vs. time t

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t .

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i , K/W	0.001672	0.005587	0.0009173	0.001746	0.00002947	0.00004815
τ_i , s	0.7362	0.2085	0.04579	0.02035	0.001151	0.0002525

DC Anode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.00210303	0.01274	0.004665	0.002034	0.0003912	0.00006677
τ_i , s	0.9538	1.844	0.1973	0.0273	0.01317	0.0003452

DC Cathode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.00174876	0.008842	0.004885	0.001938	0.0005191	0.00006714
τ_i , s	0.8698	1.832	0.1954	0.02828	0.01423	0.0003478

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

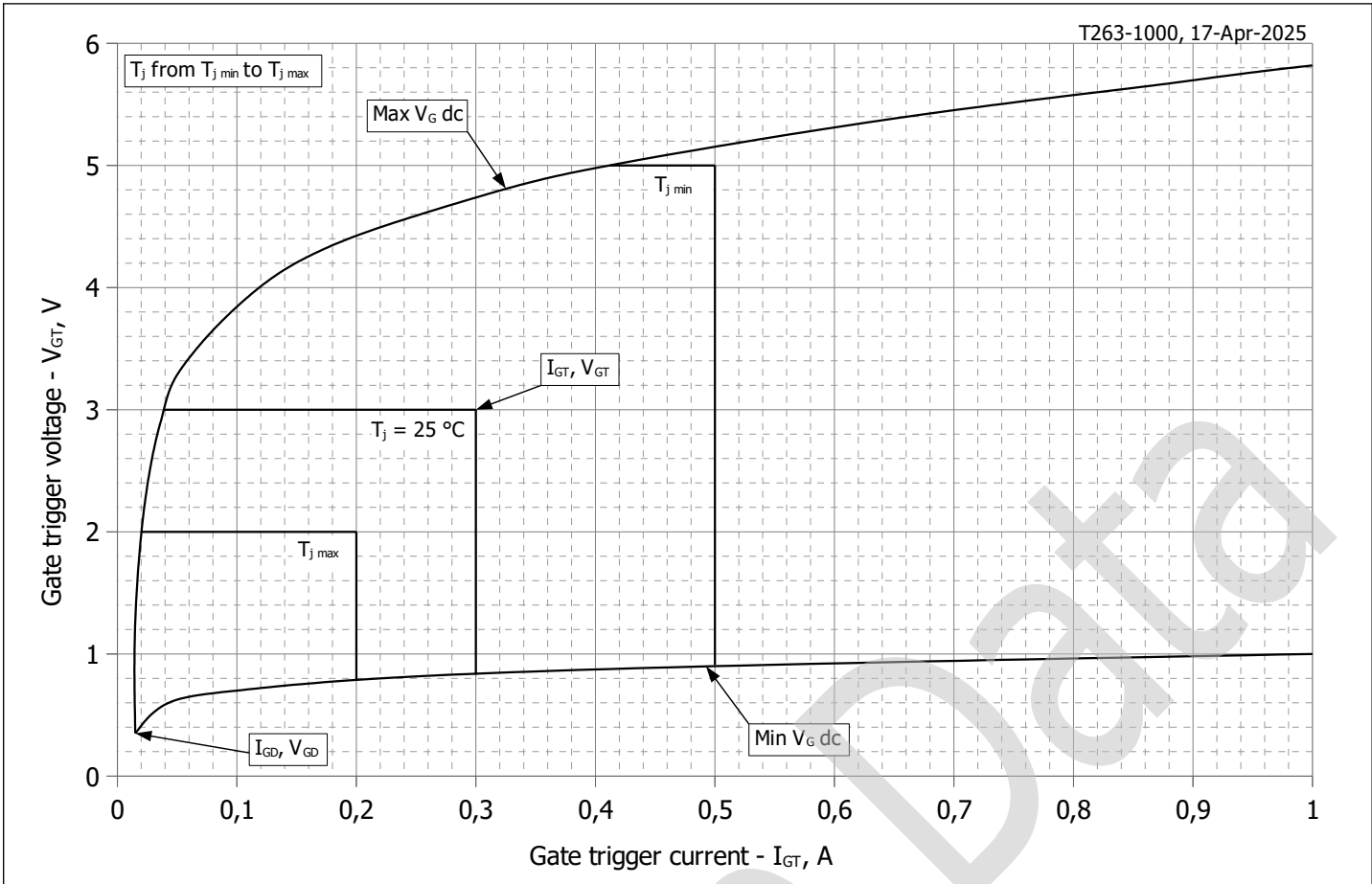


Fig 3 – Gate characteristics – Trigger limits



Fig 4 - Gate characteristics – Power curves

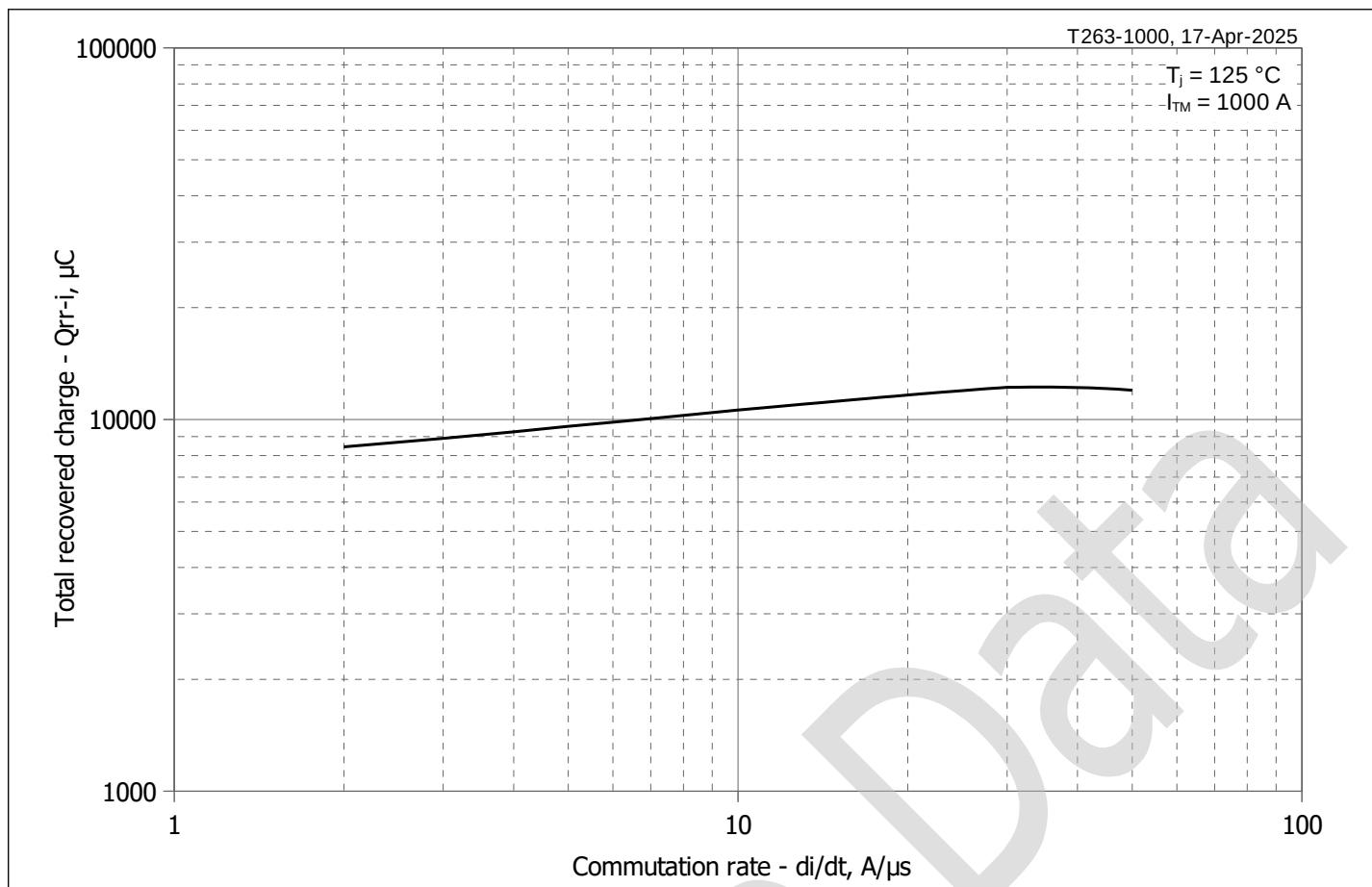


Fig 5 – Maximum recovered charge Q_{rr-i} (integral) vs. commutation rate di_R/dt



Fig 6 – Maximum recovered charge Q_{rr} vs. commutation rate di_R/dt (25% chord)

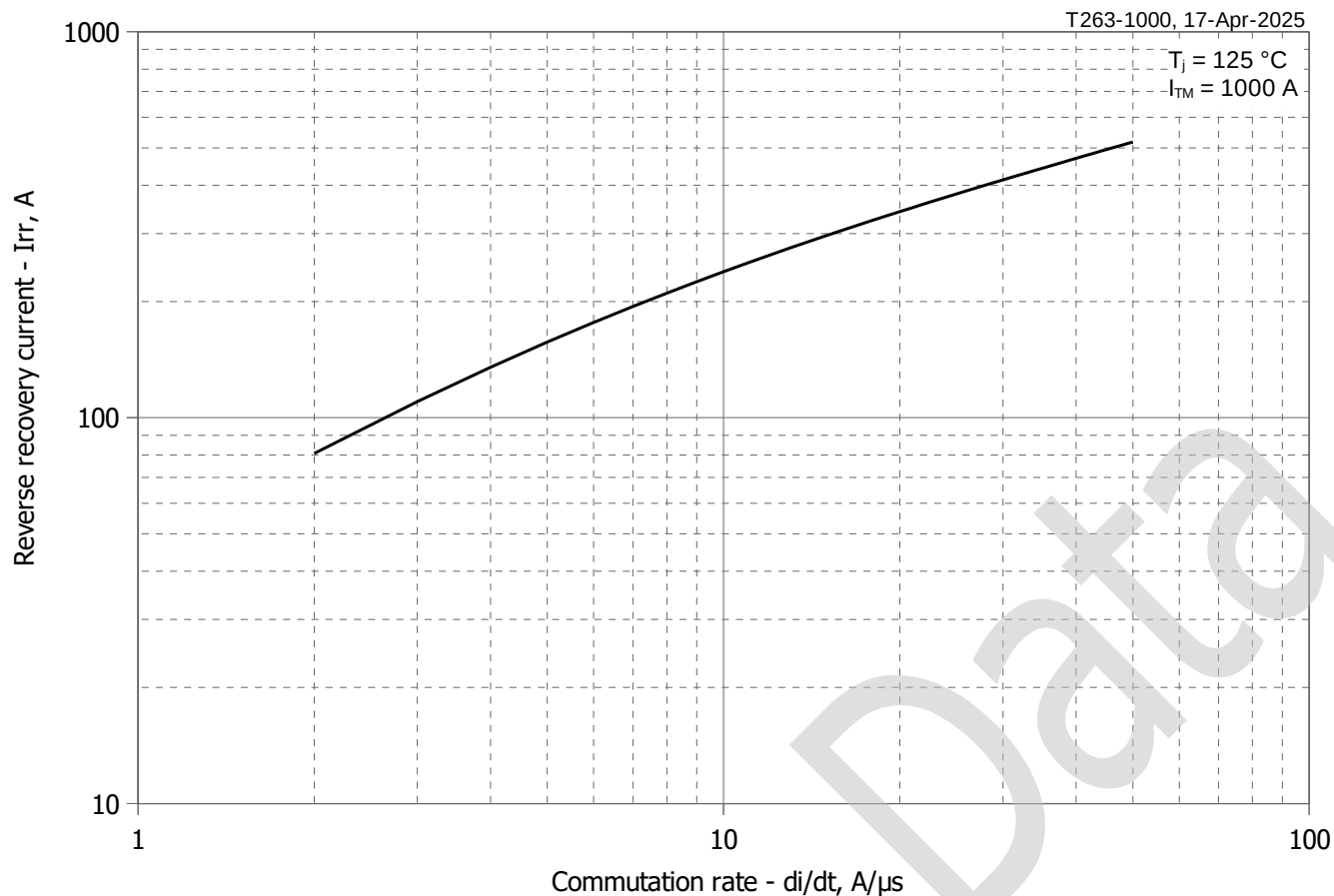


Fig 7 – Maximum reverse recovery current I_{rr} vs. commutation rate di_R/dt

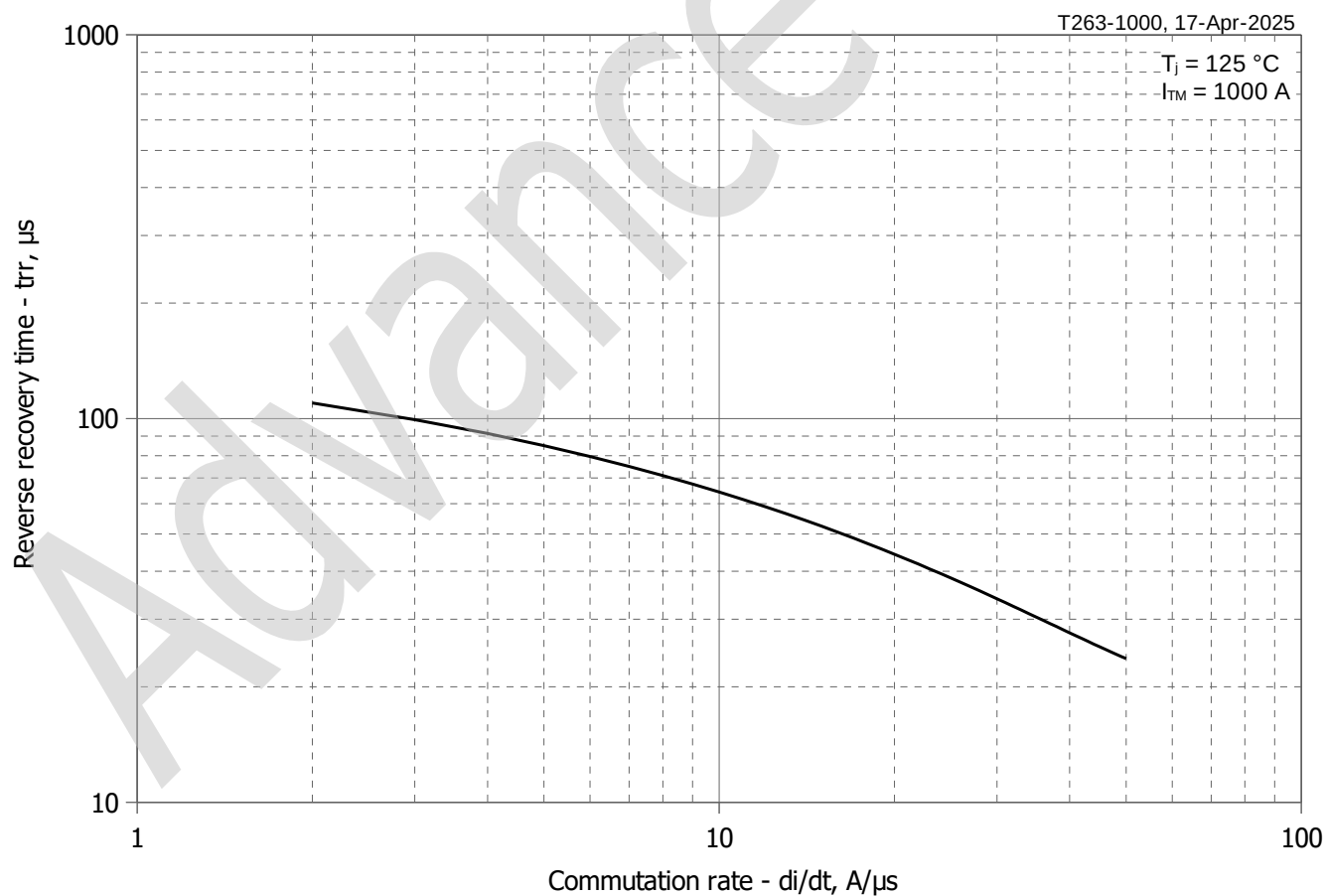


Fig 8 – Maximum recovery time t_{rr} vs. commutation rate di_R/dt (25% chord)

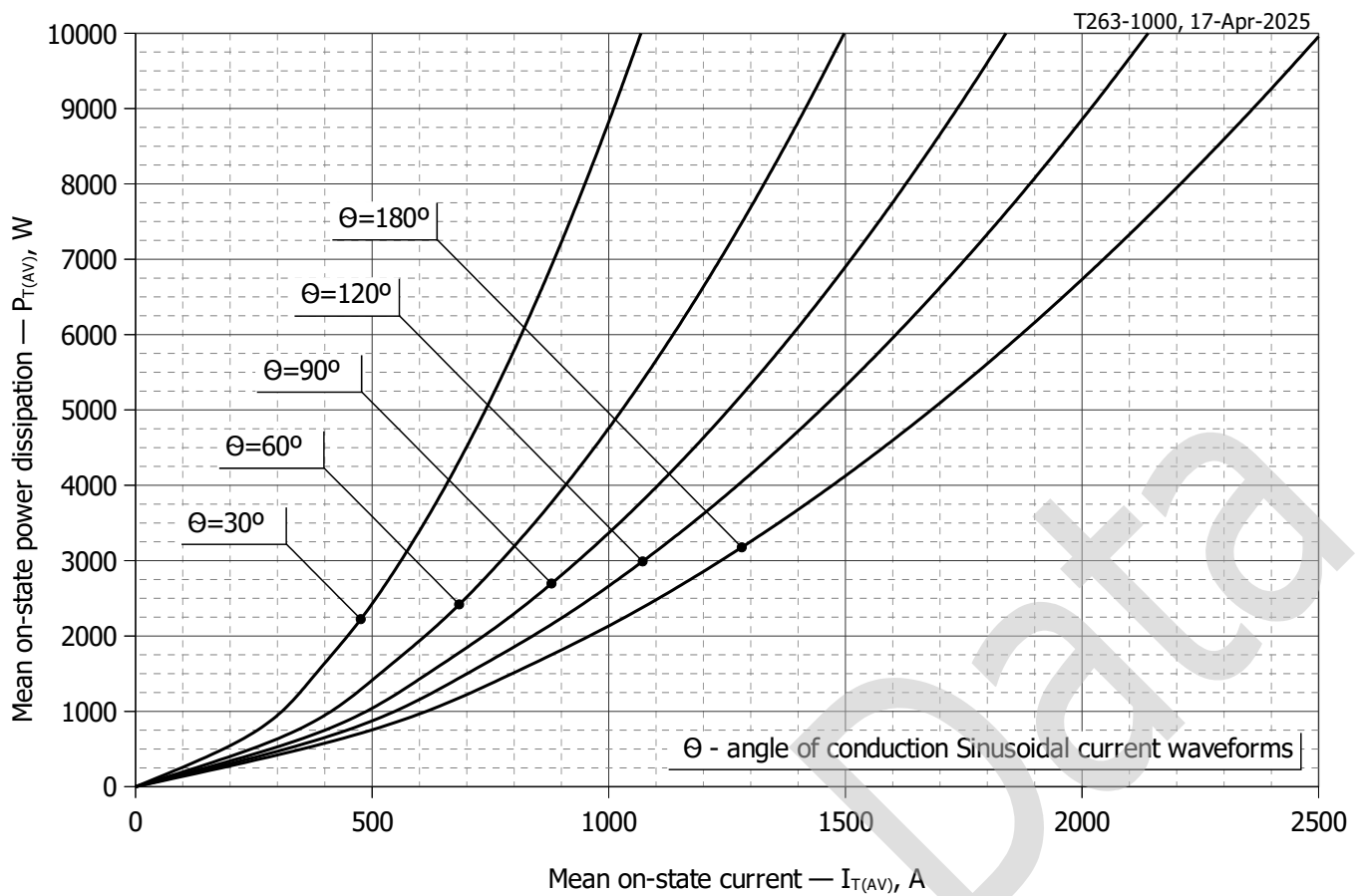


Fig. 9 - Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for sinusoidal current waveforms at different conduction angles ($f=50\text{Hz}$, DSC)

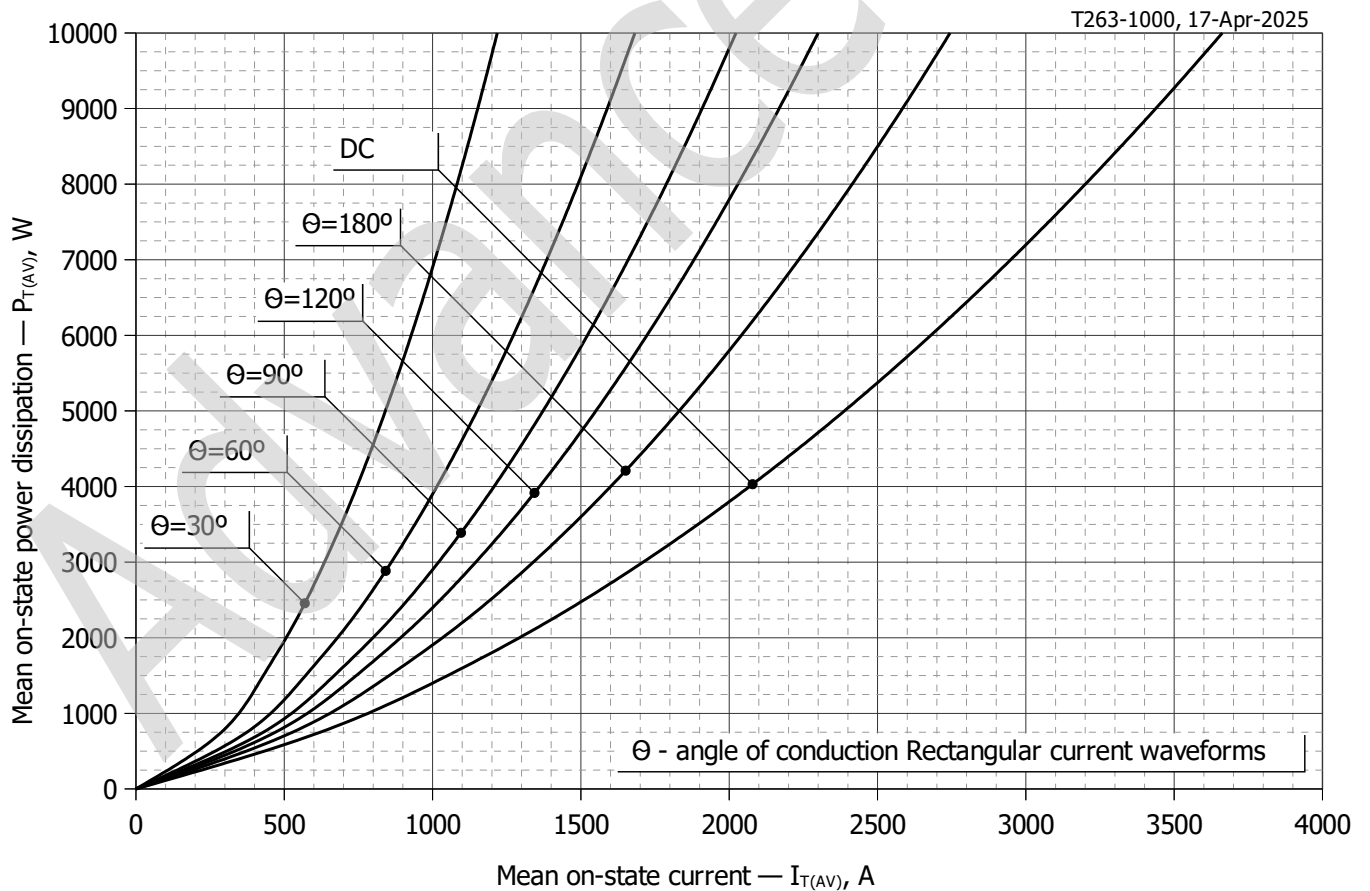


Fig. 10 – Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for rectangular current waveforms at different conduction angles and for DC ($f=50\text{Hz}$, DSC)

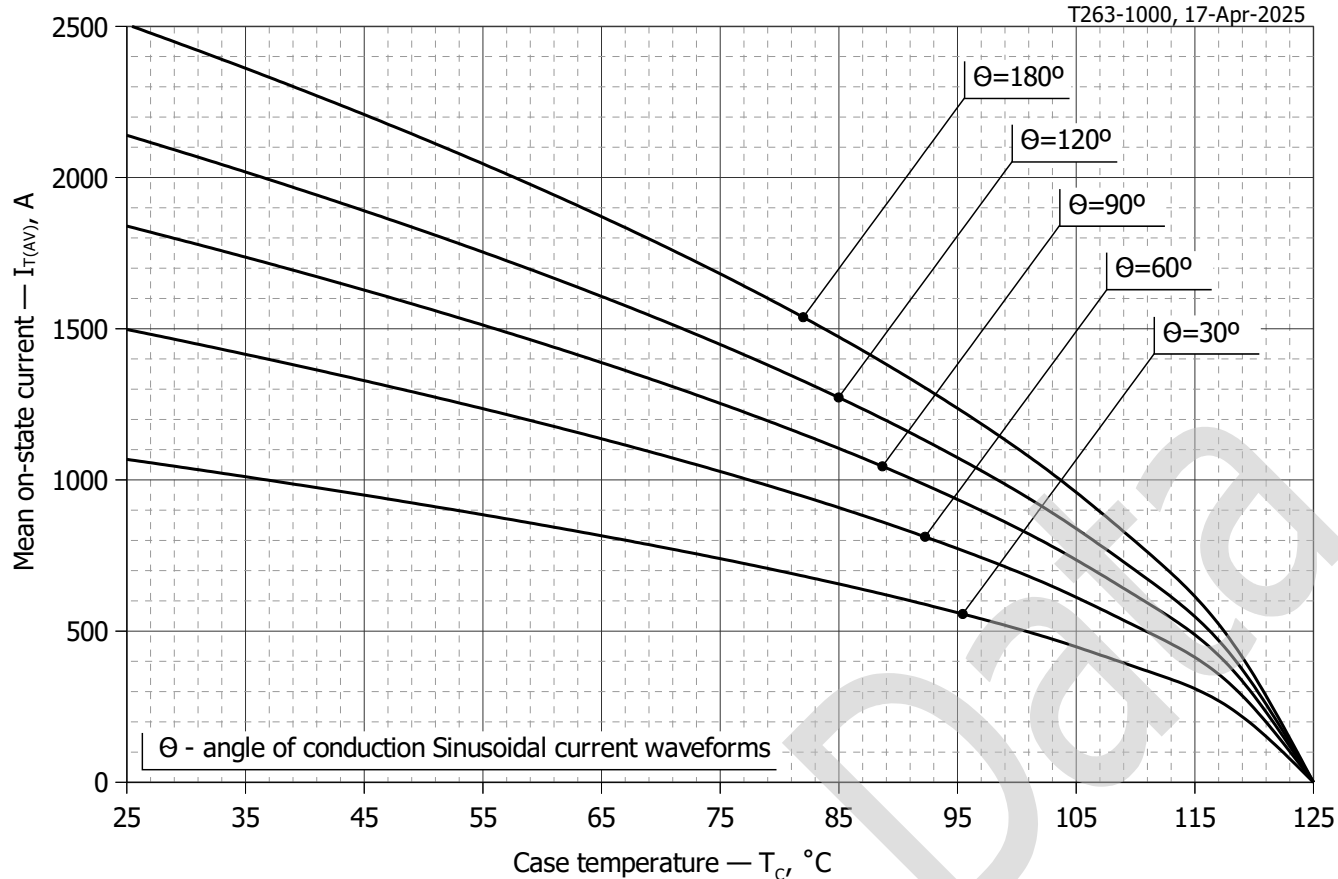


Fig. 11 – Mean on-state current I_{TAV} vs. case temperature T_c for sinusoidal current waveforms at different conduction angles ($f=50\text{Hz}$, DSC)

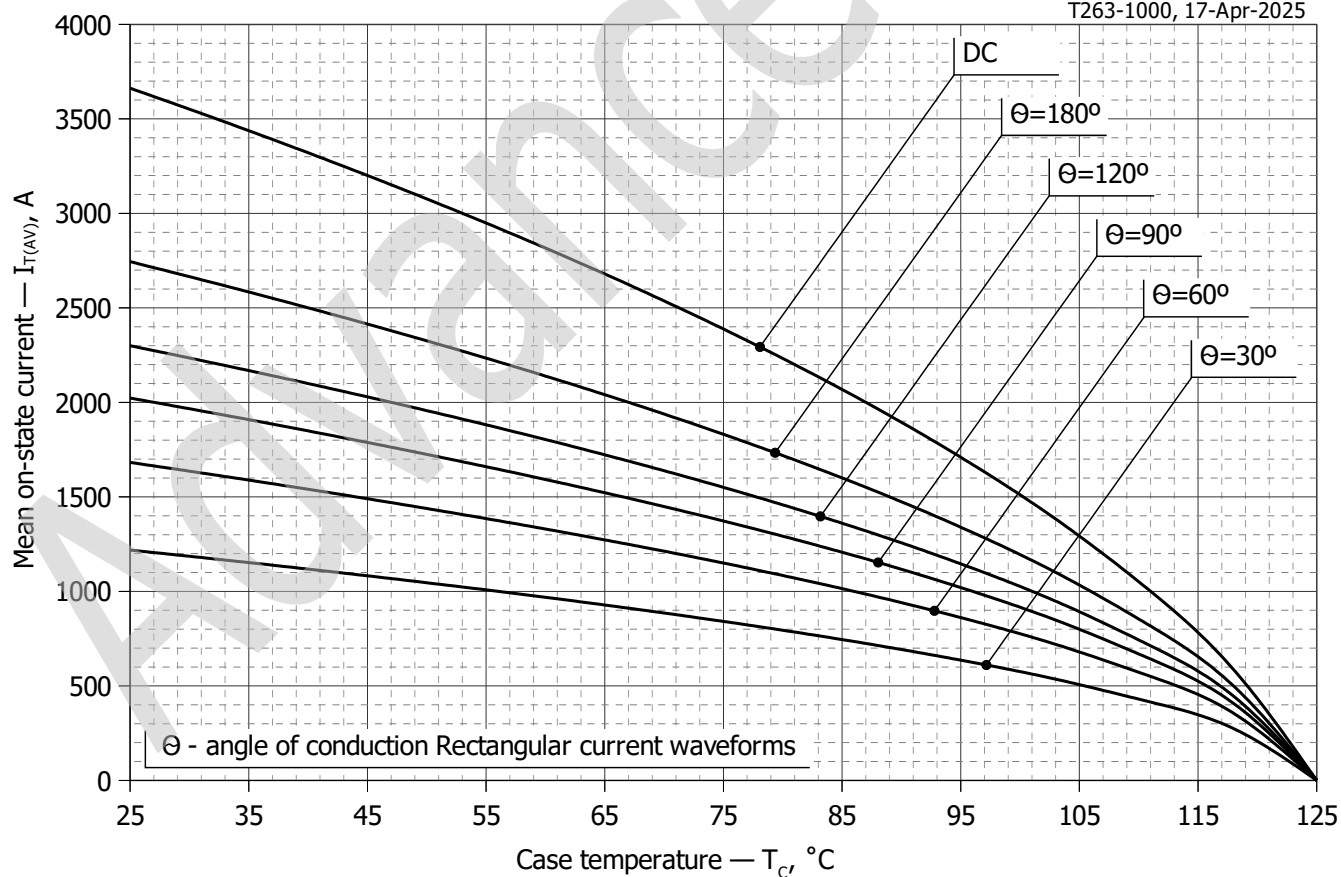


Fig. 12 - Mean on-state current I_{TAV} vs. case temperature T_c for rectangular current waveforms at different conduction angles and for DC ($f=50\text{Hz}$, DSC)

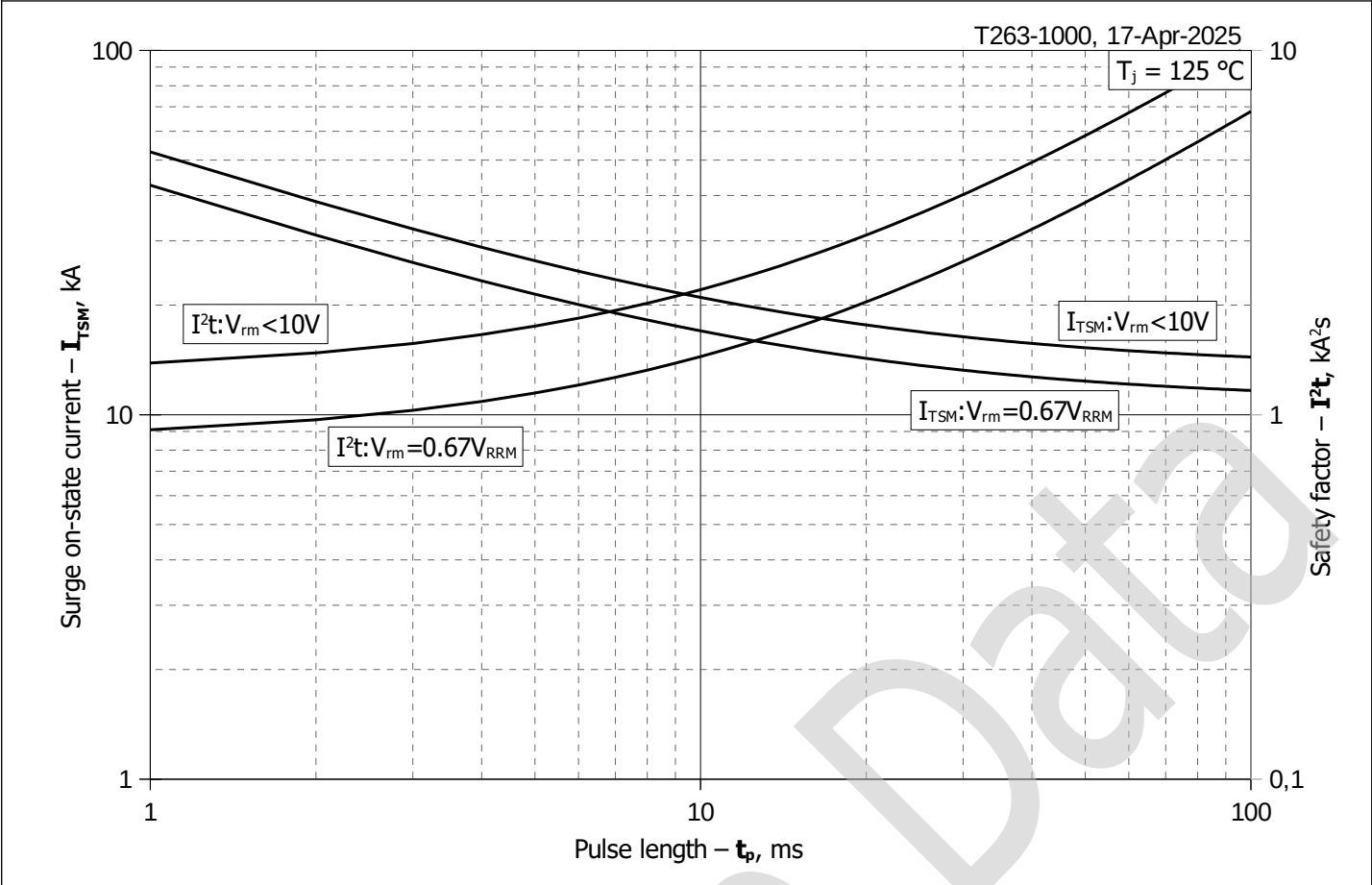


Fig. 13 – Maximum surge on-state current I_{TSM} and safety factor I^2t vs. pulse length t_p

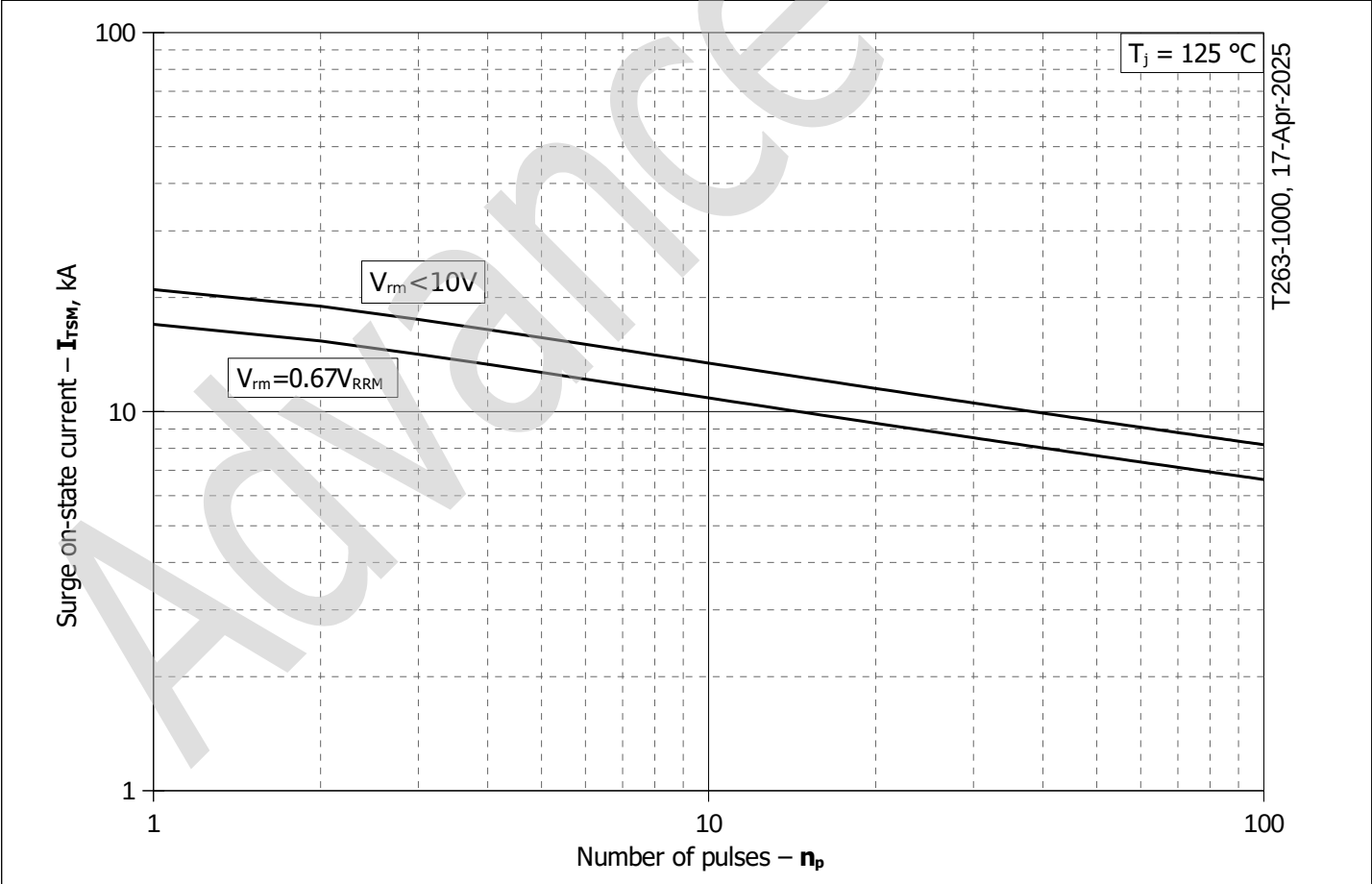


Fig. 14 - Maximum surge on-state current I_{TSM} vs. number of pulses n_p